

## SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIER

### Features

- ◆ Glass Passivated Chip Junction
- ◆ Ideal for surface mouted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:
- ◆ 250°C/10 seconds, 0.375" (9.5mm) lead length, 5 lbs. (2.3kg) tension

### Mechanical Data

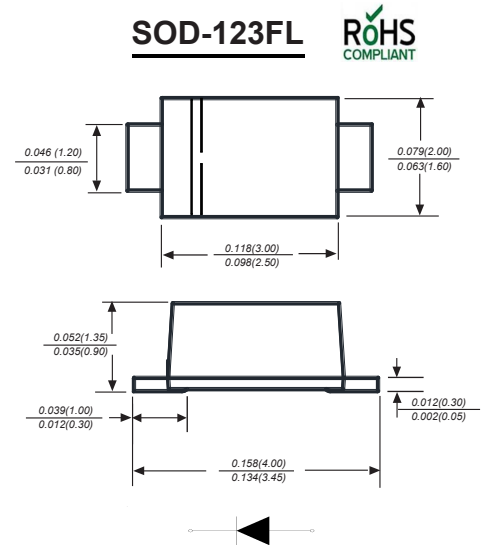
Case : JEDEC UOD-123FL molded plastic body

Terminals : Solderable per MIL-STD-750, Method 2026A

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0053 ounce, 0.015grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	S2AW	S2BW	S2DW	S2GW	S2JW	S2KW	S2MW	UNITS
Marking Code		2A1	2A2	2A3	2A4	2A5	2A6	2A7	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at TL(see fig.1)	$I_{(AV)}$	2.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50							A
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.1							V
Maximum DC reverse current $T_A=25^{\circ}C$ at rated DC blocking voltage $T_A=125^{\circ}C$	$I_R$	5 50							$\mu A$
Typical junction capacitance (NOTE 1)	$C_J$	25							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$ $R_{\theta JC}$	75 22							$^{\circ}C/W$
Operating junction temperature range	$T_J$	-55 to +150							$^{\circ}C$
Storage temperature range	$T_{STG}$	-55 to +150							$^{\circ}C$

Note: 1. Averaged over any 20ms period.

2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

3. Thermal resistance from junction to ambient at 0.375" (9.5mm) lead length, P.C.B. mounted

## Typical Characteristics

Fig.1 Forward Current Derating Curve

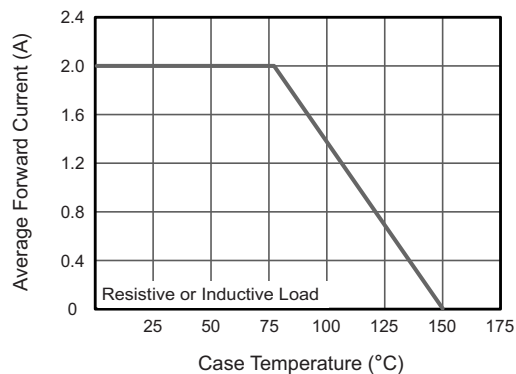


Fig.2 Typical Instantaneous Reverse Characteristics

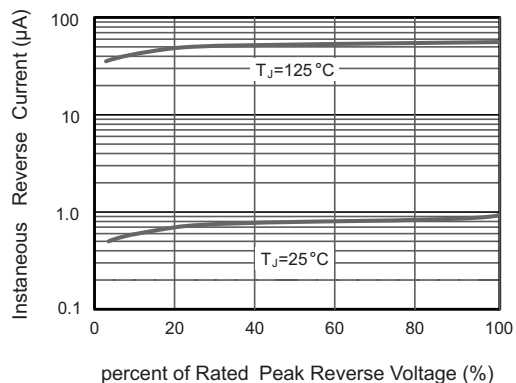


Fig.3 Typical Forward Characteristic

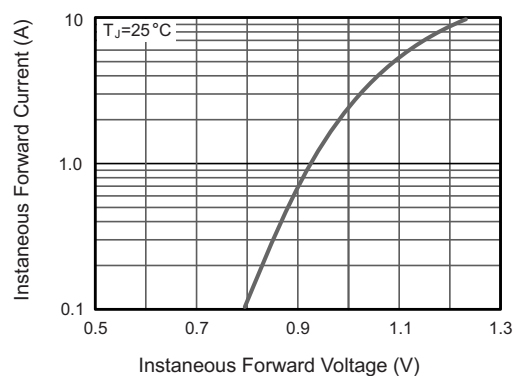


Fig.4 Typical Junction Capacitance

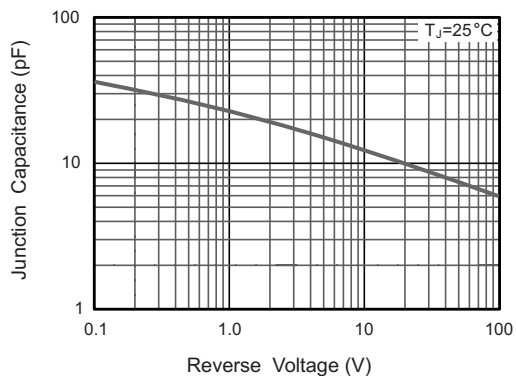
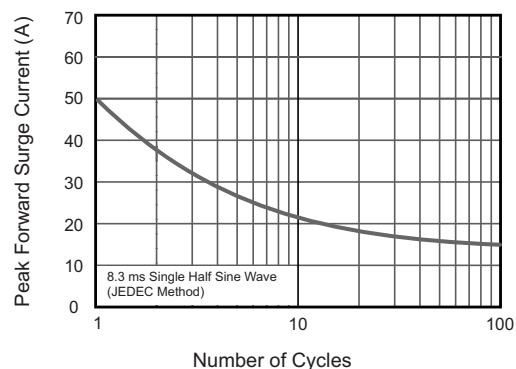
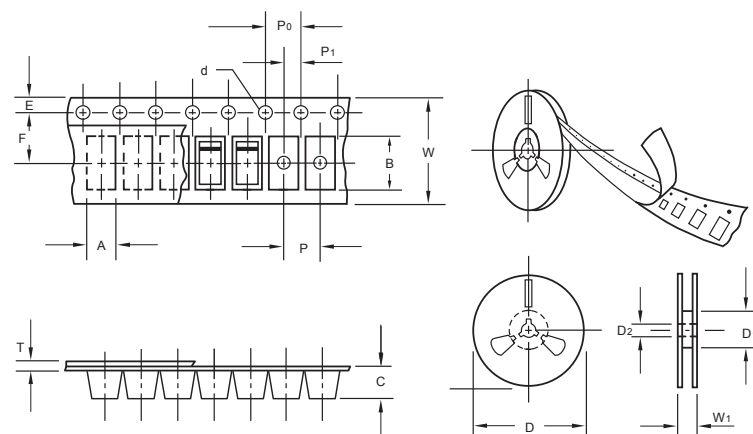


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

## Packing information



unit:mm

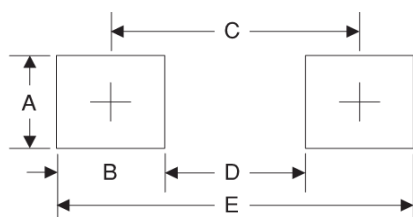
Item	Symbol	Tolerance	SOD-123FL
Carrier width	A	0.1	2.1
Carrier length	B	0.1	4.0
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.0
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W1	1.0	10.5

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)
SOD-123FL	7"	3,000	4.0	45,000	190*190*190	178	400*400*220	180,000

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	3.2	0.126
D	2	0.079
E	4.4	0.173

## Important Notice and Disclaimer

Microdiode Electronics (Shenzhen) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.

Microdiode Electronics (Shenzhen) makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Microdiode Electronics (Shenzhen) assume any liability for application assistance or customer product design. Microdiode Electronics (Shenzhen) does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Microdiode Electronics (Shenzhen).

Microdiode Electronics (Shenzhen) products are not authorized for use as critical components in life support devices or systems without express written approval of Microdiode Electronics (Shenzhen).